

300 mm wafer services

ENERGY DEVICES

ANALYTICAL SERVICES

SCREENING FAB SERVICES

Wafer Services

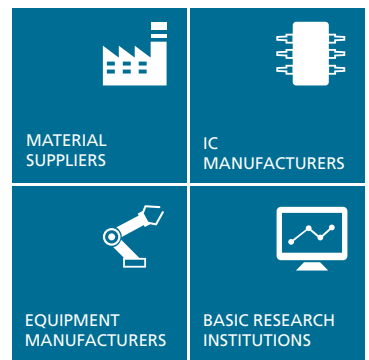
For high volume production (HVM) of semiconductor devices such as microprocessors, every single process step is of interest for evaluation and optimization. Test vehicles and test wafers are essential for testing developments and new materials under production conditions.

Test wafers enable scientists to react quickly on process changes and transfer chemicals or processes from »Lab to Fab« for HVM.

The Fraunhofer IPMS business unit CNT is intensively researching the production and optimization of semiconductor devices and offers a multitude of advantages.

Advantages at CNT

- Established test platform for micro- and nanoelectronic products
- Direct wafer exchange with production lines of manufacturer and supplier
- Industry standard clean room with 300/200 mm equipment
- Independent evaluation, experiment planning from process and equipment experts with over 10 years experience
- Designing of layouts, layer stacks and material properties
- Test wafers from CNT are verified in our metrology system park for a fast realization of further qualification steps on site
- ISO9001 quality and contamination management



Contact

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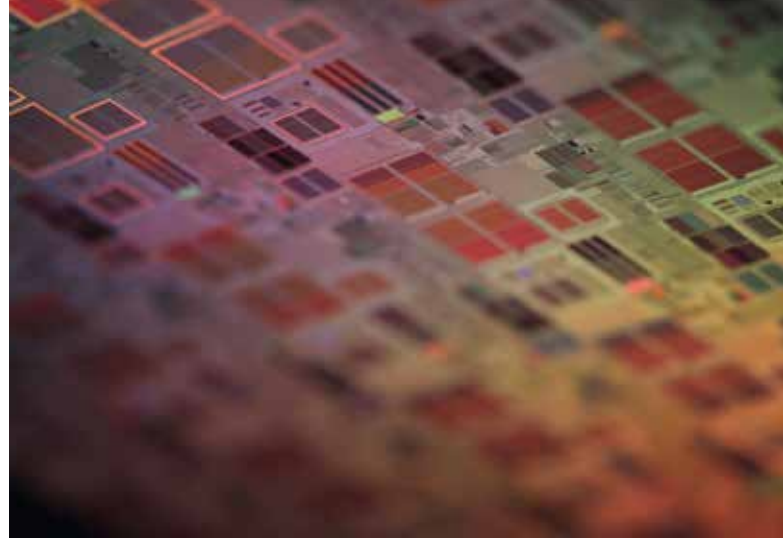
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www.ipms.fraunhofer.de
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Blank wafer



Structured wafer

300 mm wafer services

BLANK WAFER

SILICON BASED LAYERS

- SiO₂ (thermal or chemical formed oxide)
- Organo silicate glass (SiCOH/ULK) [porous]
- SiGe
- Doped amorphous silicon (P,B)

METALS

- PVD: Ta(N), Ti(N), Cu, W, Hf(Ox), Si, W, Co, CoFe(B), Ir, Pt, Ru, Mo
- CVD: Co
- ECD: Co, Cu

ALD BASED OXIDES & NITRIDES

- Al₂O₃
- HfO₂ (doped)
- ZrO₂
- HZO

More materials upon request

STRUCTURED WAFER

TEST STRUCTURES FOR VARIOUS PROCESSES AT ≤ 28 NM TECHNOLOGY NODE

- CMP | Plating | Cleaning
- Thin films | STI

TEST STRUCTURES FOR FUNCTIONAL LAYERS

- Memory applications (FRAM, RRAM, MRAM,...)
- MIS/MIM Structures

CUSTOM LAYOUT IMPLEMENTATION E-BEAM LITHOGRAPHY NANOPATTERNIG

- Small series
- Complementary »Mix & Match« layout

METROLOGY

- Layer thickness and uniformity (4-point probing, ellipsometry, XRR, high resolution profilometry)
- Film morphology and structure (AFM [3D], XRD, surface inspection, SEM, TEM, porosimetry)
- Chemical composition & contamination (ToF-SIMS, XPS, TXRF, REELS, ICP-MS, AAS)
- Patterned defect inspection
- Electrochemical monitoring of electrolyte solutions and additives (CVS, LP, EIS, etc.)
- Electrical characterization of functional layers and layer stacks (semi-automatic probing)
- Test wafers are verified in our metrology system park for a fast realization of further qualification steps on site
- Full process catalogue: www.screening-fab.com

